



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	2.5mΩ@10V	140A
	2.9mΩ@4.5V	

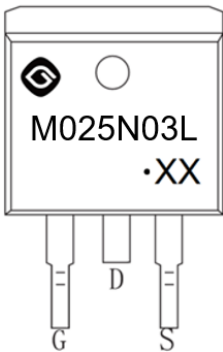
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application

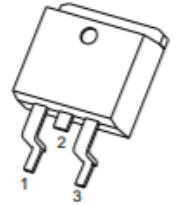
MARKING:



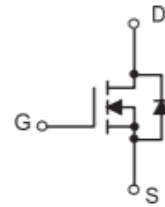
M025N03L = Device Code
XX = Date Code
Solid Dot = Green Indicator

TO-263-2L

1. GATE
2. DRAIN
3. SOURCE



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain - Source Voltage	V_{DS}	30	V	
Gate - Source Voltage	V_{GS}	±20	V	
Continuous Drain Current ¹	I_D	$T_C = 25^\circ\text{C}$	140	A
Continuous Drain Current ¹		$T_C = 100^\circ\text{C}$	90	A
Pulsed Drain Current ²	I_{DM}	560	A	
Single Pulsed Avalanche Current ³	I_{AS}	53	A	
Single Pulsed Avalanche Energy ³	E_{AS}	702	mJ	
Power Dissipation ⁵	P_D	$T_C = 25^\circ\text{C}$	150	W
Thermal Resistance from Junction to Ambient ⁶		$R_{\theta JA}$	50	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1	$^\circ\text{C/W}$	
Junction Temperature	T_J	175	$^\circ\text{C}$	
Storage Temperature	T_{STG}	-55~ +175	$^\circ\text{C}$	

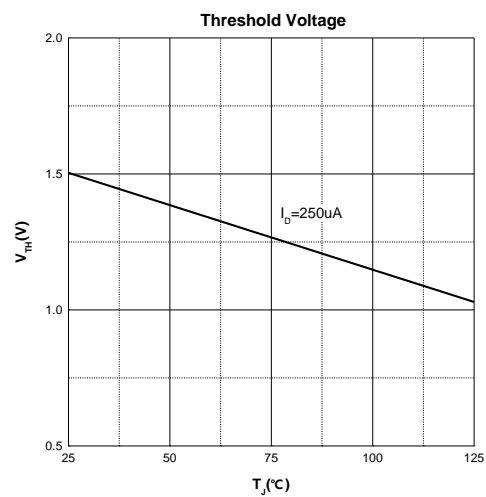
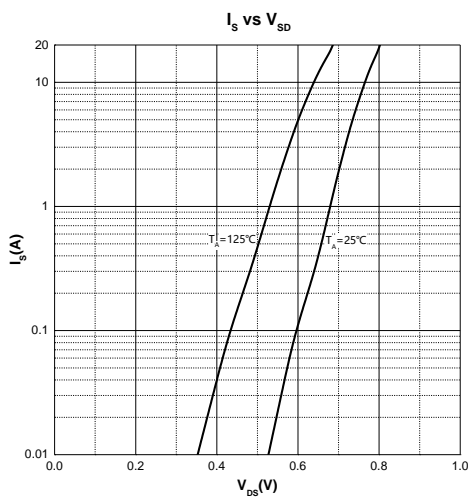
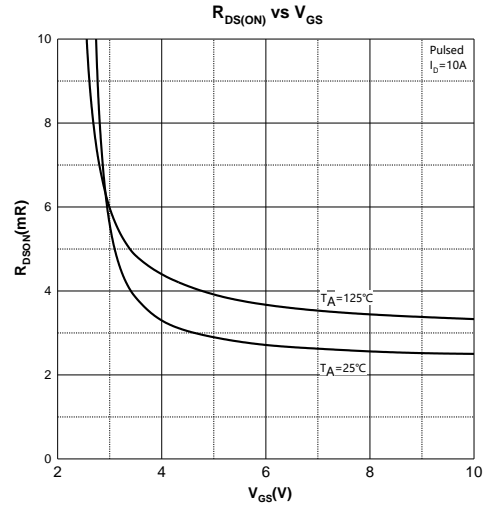
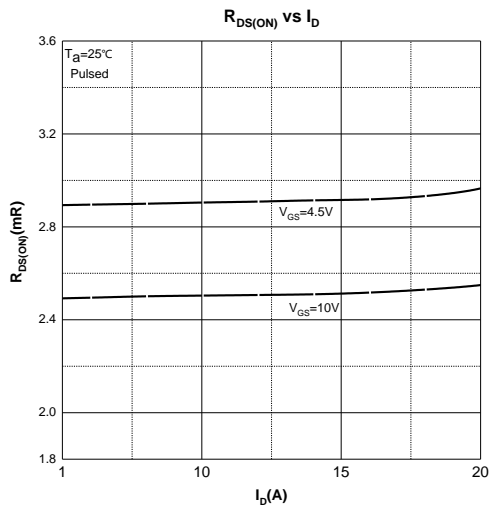
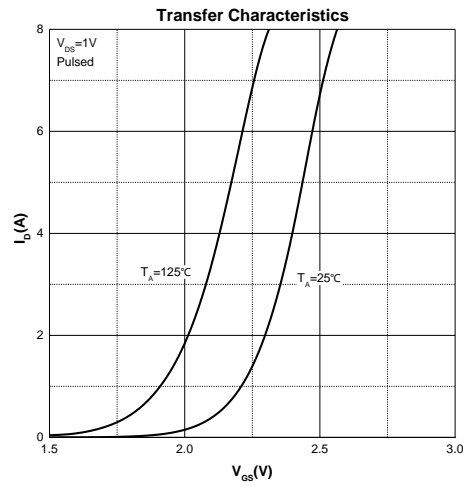
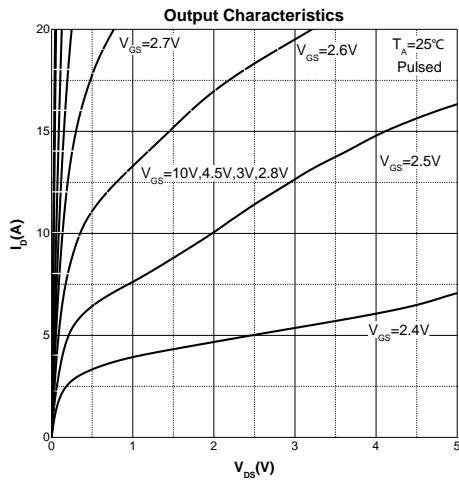
MOSFET ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

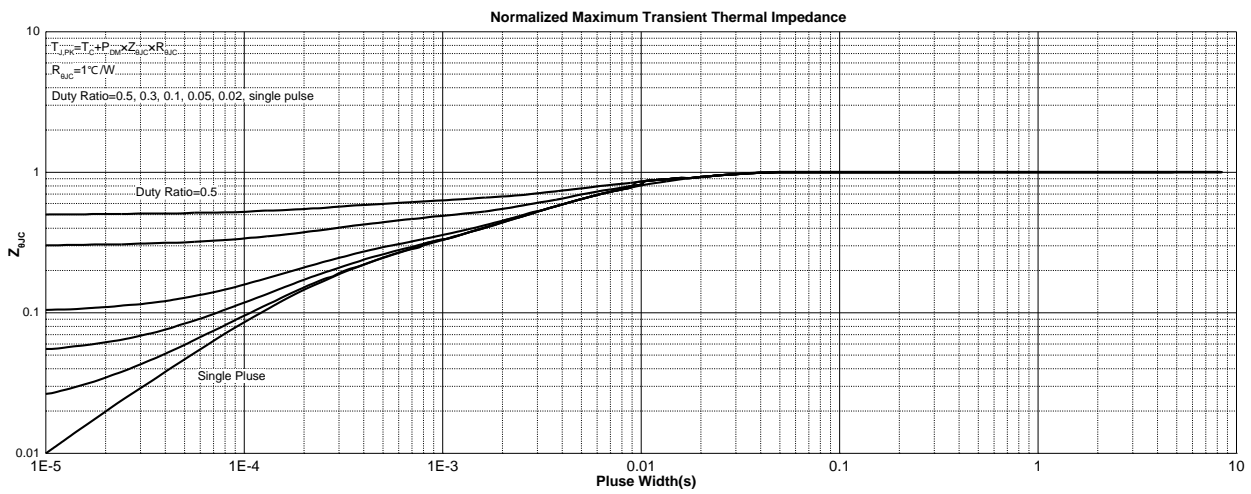
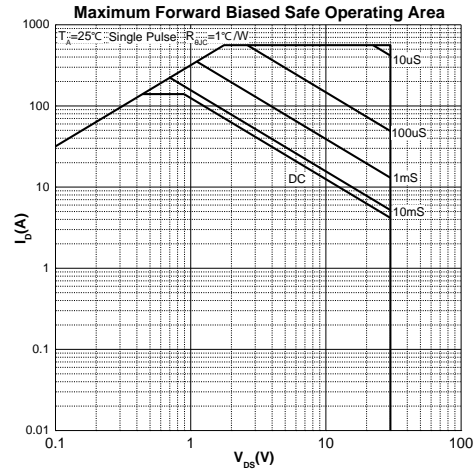
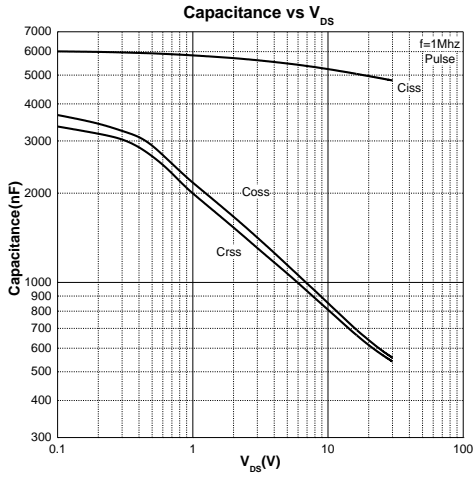
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.5	3.0	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		2.5	3.1	mΩ
		V _{GS} = 4.5V, I _D = 10A		2.9	3.8	
Forward Transconductance	g _{FS}	V _{DS} = 10V, I _D = 10A	10			S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		5144		pF
Output Capacitance	C _{oss}			721		
Reverse Transfer Capacitance	C _{rss}			688		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		1		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = 15V, V _{GS} = 10V, I _D = 20A		120		nC
Gate-source Charge	Q _{gs}			16		
Gate-drain Charge	Q _{gd}			37		
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15V, V _{GS} = 10V, R _L = 0.75Ω R _G = 3Ω		18		ns
Turn-on Rise Time	t _r			22		
Turn-off Delay Time	t _{d(off)}			52		
Turn-off Fall Time	t _f			20		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = 10A			1.2	V

Notes :

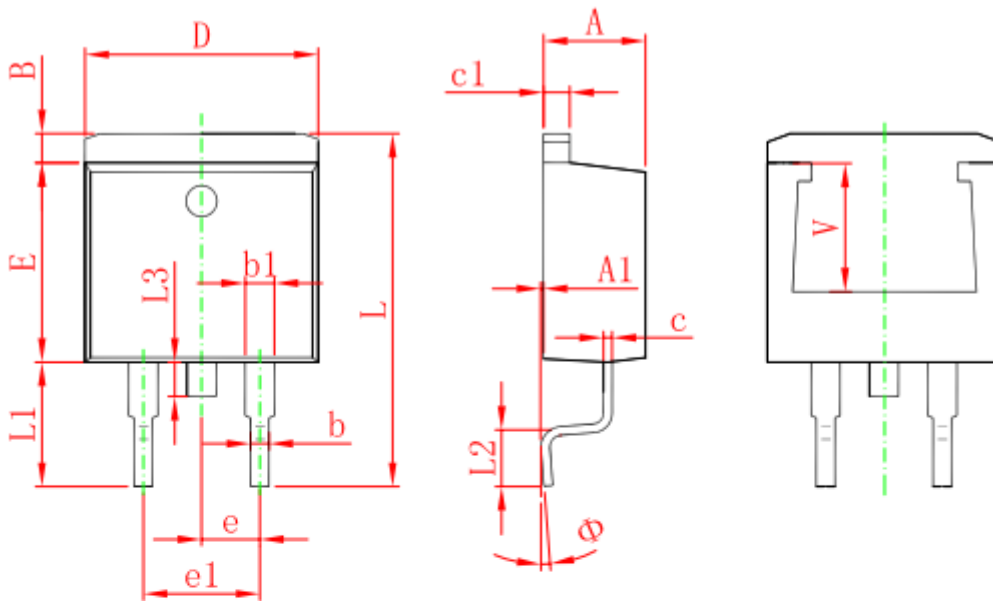
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
- 3.E_{AS} condition: V_{DD} = 25V, V_{GS} = 10V, L = 0.5mH, R_G = 25Ω Starting T_J = 25°C.
- 4.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
- 5.The power dissipation P_D is limited by T_{J(MAX)} = 150°C.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.

Typical Characteristics





TO-263-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
Φ	0°	8°	0°	8°
V	5.600 REF.		0.220 REF.	